

PCN Number:	20171218003		PCN Date:	Dec 19, 2017						
Title:	Qualification of UTAC as an additional Assembly and Test Site for Select Devices									
Customer Contact:	PCN Manager	Dept:	Quality Services							
Proposed 1st Ship Date:	Mar 19, 2018	Estimated Sample Availability:	Provided upon Request							
Change Type:										
<input checked="" type="checkbox"/>	Assembly Site	<input checked="" type="checkbox"/>	Assembly Process	<input checked="" type="checkbox"/>	Assembly Materials					
<input type="checkbox"/>	Design	<input type="checkbox"/>	Electrical Specification	<input type="checkbox"/>	Mechanical Specification					
<input checked="" type="checkbox"/>	Test Site	<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process					
<input type="checkbox"/>	Wafer Bump Site	<input type="checkbox"/>	Wafer Bump Material	<input type="checkbox"/>	Wafer Bump Process					
<input type="checkbox"/>	Wafer Fab Site	<input type="checkbox"/>	Wafer Fab Materials	<input type="checkbox"/>	Wafer Fab Process					
		<input type="checkbox"/>	Part number change							
PCN Details										
Description of Change:										
Texas Instruments is pleased to announce the qualification of subcontractor UTAC as an alternate Assembly and Test site. Material construction differences are as follows:										
<table border="1"> <thead> <tr> <th>What</th> <th>PSI</th> <th>UTAC</th> </tr> </thead> <tbody> <tr> <td>Bond Wire/Diameter</td> <td>Au, 1.0 mil</td> <td>Cu, 1.0 mil</td> </tr> </tbody> </table>					What	PSI	UTAC	Bond Wire/Diameter	Au, 1.0 mil	Cu, 1.0 mil
What	PSI	UTAC								
Bond Wire/Diameter	Au, 1.0 mil	Cu, 1.0 mil								
Test coverage, insertions, conditions will remain consistent with current testing and verified with test MQ.										
Reason for Change:										
Continuity of Supply										
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):										
None										
Anticipated impact on Material Declaration										
<input type="checkbox"/>	No Impact to the Material Declaration	<input checked="" type="checkbox"/>	Material Declarations or Product Content reports are driven from production data and will be available following the production release. Upon production release the revised reports can be obtained from the TI ECO website .							

Changes to product identification resulting from this PCN:			
Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (21L)	Assembly City
PSI	PS2	PHL	Calamba City
UTAC	NSE	THA	Bangkok
Sample product shipping label (not actual product label)			



MADE IN: Malaysia
2DC: 2Q:

MSL '2 /260C/1 YEAR	SEAL DT
MSL 1 /235C/UNLIM	03/29/04

OPT:
ITEM: 39
LBL: 5A (L)T0:1750



(1P) SN74LS07NSR
(Q) 2000 (D) 0336
(31T) LOT: 3959047MLA
(4W) TKY (1T) 7523483SI2
(P)
(2P) REV: (V) 0033317
(20L) CSO: SHE (21L) CCO:USA
(22L) ASO: MLA (23L) ACO: MYS

Product Affected

CSD59952RWJ	CSD95482RWJ	CSD95482RWJT
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TI Information
Selective Disclosure

Qualification Report

CSD95482RWJ QUAL PLAN - UTAC (QBS to CSD95480RWJ)
Approve Date 11-Dec-2017

Product Attributes

Attributes	Qual Device: CSD95482RWJ	Qual Device: CSD95482RWJ	QBS Product Reference: CSD5995ARWJ	QBS Product Reference: CSD95480RWJ
Wafer Fab Supplier	FFAB CFAB CFAB	MIHO CFAB CFAB	MIHO CFAB CFAB	MIHO CFAB CFAB
Wafer Process	LBC7 NEXFET GEN2.2 LV2010 NEXFET GEN2.2 LV2010	LBC7 NEXFET GEN2.2 LV2010 NEXFET GEN2.2 LV2010	LBC7 NEXFET GEN2.2 LV2010 NEXFET GEN2.2 LV2010	LBC7 NEXFET GEN2.2 LV2010 NEXFET GEN2.2 LV2010
Assembly Site	UTAC	UTAC	UTAC	UTAC
Package Family	QFN/SON	QFN/SON	QFN/SON	QFN/SON

- QBS: Qual By Similarity

- Qual Devices qualified at LEVEL 1-260C: CSD59952RWJ CFAB/MIHO, CSD59952RWJ CFAB/FFAB, CSD95482RWJ CFAB/FFAB, CSD95482RWJ CFAB/MIHO

- Devices contain multiple dies: CSD95482RWJ CFAB/MIHO, CSD59952RWJ CFAB/MIHO, CSD95482RWJ CFAB/FFAB, CSD59952RWJ CFAB/FFAB

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: CSD95482RWJ	Qual Device: CSD95482RWJ	QBS Product Reference: CSD5995ARWJ	QBS Product Reference: CSD95480RWJ
AC	Autoclave 121C	96 Hours	-	-	-	3/231/0
ED	Electrical Characterization	Per Datasheet Parameters	-	-	Pass	-
HAST	Biased HAST, 130C/85%RH	96 Hours	-	-	-	3/231/0
HBM	ESD - HBM	3000 V	-	-	1/3/0	-
CDM	ESD - CDM	2000 V	-	-	1/3/0	-
HTOL	Life Test, 125C	1000 Hours	-	-	3/231/0	3/231/0
HTSL	High Temp. Storage Bake, 150C	1000 Cycles	-	-	-	3/231/0
IOL	Dynamic Intermittent Operating Life	10000 Cycles (4 min Cycles)	-	-	-	3/231/0
LU	Latch-up	(per JESD74)	-	-	1/6/0	-
TC	Temperature Cycle, -55/125C	700 Cycles	-	-	-	3/231/0
WBP	Bond Pull	Wires	1/76/0	2/152/0	1/76/0	3/228/0
WBS	Ball Bond Shear	Wires	1/76/0	2/152/0	1/76/0	3/228/0
YLD	FTY and Bin Summary	-	Pass	Pass	Pass	Pass

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

- The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

- The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours

- The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -55C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
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